

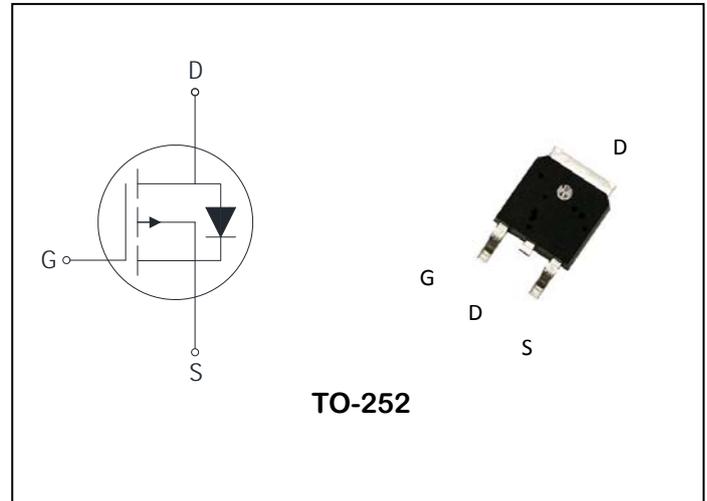
## P-Channel Logic Level Enhancement Mode Field Effect Transistor

### PRODUCT SUMMARY

$V_{DSS}$	$I_D$	$R_{DS(ON)}$ (m $\Omega$ )
-60V	-35A	28m $\Omega$

### Features:

- Low Gate Charge for Fast Switching Application
- Fast Switching
- Improved dv/dt Capability
- Green Device Available



### Description:

These P-Channel enhancement mode power field effect transistors are using trench DMOS technology. design to provide excellent  $R_{DS(ON)}$  with low gate charge. provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

### Absolute Maximum Ratings ( $T_A = 25^\circ\text{C}$ unless otherwise specified )

Symbol	Parameter		Ratings	Unit
<b>Common Ratings</b>				
$V_{DSS}$	Drain-Source Voltage		-60	V
$V_{GSS}$	Gate-Source Voltage		$\pm 20$	
$T_J$	Maximum Junction Temperature		150	$^\circ\text{C}$
$T_{STG}$	Storage Temperature Range		-55 to 150	$^\circ\text{C}$
$I_S$	Diode Continuous Forward Current	$T_C = 25^\circ\text{C}$	-35	A
<b>Mounted on Large Heat Sink</b>				
$I_{DM}$	300 $\mu\text{s}$ Pulse Drain Current Tested <sup>(2)</sup>	$T_C = 25^\circ\text{C}, V_{GS} = -10\text{V}$	-140	A
$I_D$	Continuous Drain Current <sup>(1)</sup>	$T_C = 25^\circ\text{C}, V_{GS} = -10\text{V}$	-35	A
		$T_C = 100^\circ\text{C}$ $V_{GS} = -10\text{V}$	-22.1	A
$P_D$	Maximum Power Dissipation	$T_C = 25^\circ\text{C}$	72.6	W

### Thermal Characteristics

Symbol	Parameter	Ratings	Unit
$R_{thJC}$	Thermal resistance junction-case max <sup>(1)</sup>	1.72	$^\circ\text{C}/\text{W}$
$R_{thJA}$	Thermal resistance junction-ambient max <sup>(1)</sup>	62	$^\circ\text{C}/\text{W}$

## Electrical Characteristics (TA=25°C Unless Otherwise Noted)

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
<b>On/off Characteristics</b>						
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>DS</sub> =-250uA	-60	--	--	V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = -60V, V <sub>GS</sub> =0V T <sub>J</sub> =25°C	--	--	-1	uA
		V <sub>DS</sub> =-48V, V <sub>GS</sub> =0V T <sub>J</sub> =125°C	--	--	-10	
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>DS</sub> =-250uA	-1.0	-1.6	-2.5	V
I <sub>GSS</sub>	Gate Leakage Current	V <sub>GS</sub> = ±20V, V <sub>DS</sub> =0V	--	--	±100	nA
R <sub>DS(ON)</sub>	Drain-Source On-state Resistance <sup>(2)</sup>	V <sub>GS</sub> = -10V, I <sub>DS</sub> =-8A	--	22	28	mΩ
		V <sub>GS</sub> = -4.5V, I <sub>DS</sub> =-6A	--	26	35	
<b>Dynamic Characteristics</b>						
C <sub>iss</sub>	Input Capacitance	V <sub>GS</sub> =0V, V <sub>DS</sub> = -25V, Frequency=1.0MHz	--	2595	3900	pF
C <sub>oss</sub>	Output Capacitance		--	162	240	
C <sub>rss</sub>	Reverse Transfer Capacitance		--	115	170	
<b>Switching Characteristics</b>						
t <sub>d(ON)</sub>	Turn-on Delay Time <sup>(1)</sup>	V <sub>DD</sub> =-30V, I <sub>D</sub> = -1A, V <sub>GS</sub> = -10V, R <sub>GEN</sub> =6 Ω R <sub>L</sub> =0.94 Ω	--	25	50	ns
t <sub>r</sub>	Turn-on Rise Time <sup>(1)</sup>		--	13.8	28	
t <sub>d(OFF)</sub>	Turn-off Delay Time <sup>(1)</sup>		--	148	290	
t <sub>f</sub>	Turn-off Fall Time <sup>(1)</sup>		--	51	100	
Q <sub>g</sub>	Total Gate Charge <sup>(1)</sup>	V <sub>DS</sub> =-30V, V <sub>GS</sub> = -10V, I <sub>DS</sub> =-5A	--	43.8	88	nC
Q <sub>gs</sub>	Gate-Source Charge <sup>(1)</sup>		--	4.6	9	
Q <sub>gd</sub>	Gate-Drain Charge <sup>(1)</sup>		--	8.3	17	
<b>Avalanche Characteristics</b>						
<b>Diode Characteristics</b>						
V <sub>SD</sub>	Diode Forward Voltage <sup>(2)</sup>	I <sub>SD</sub> =-1A, V <sub>GS</sub> = 0V , T <sub>J</sub> =25°C	--	--	-1.0	V

### NOTES:

1. Surface Mounted on FR4 Board, t ≤ 10 sec.
2. The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%

## Typical Performance Characteristics

Figure 1: Continuous Drain Current vs.  $T_c$

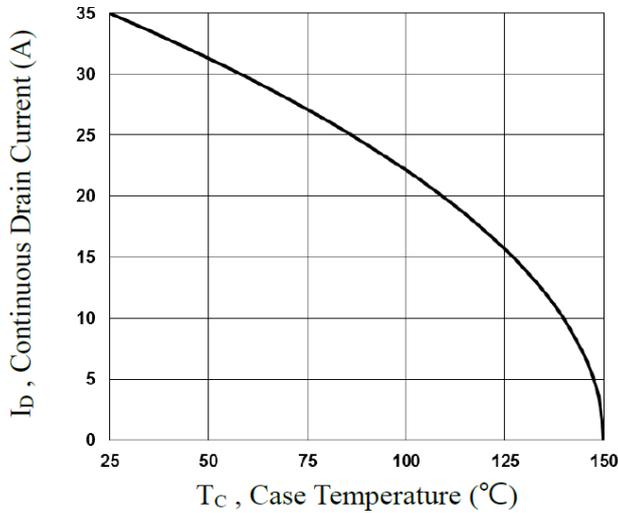


Figure 2: Normalized  $R_{DS(on)}$  vs.  $T_J$

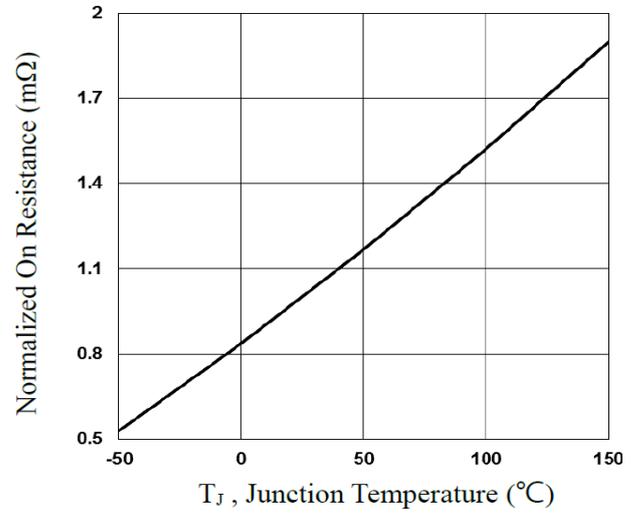


Figure 3: Normalized  $V_{th}$  vs.  $T_J$

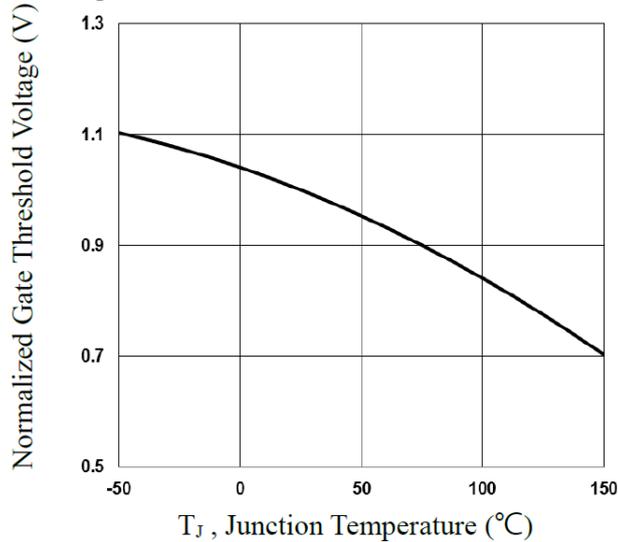


Figure 4: Gate Charge Waveform

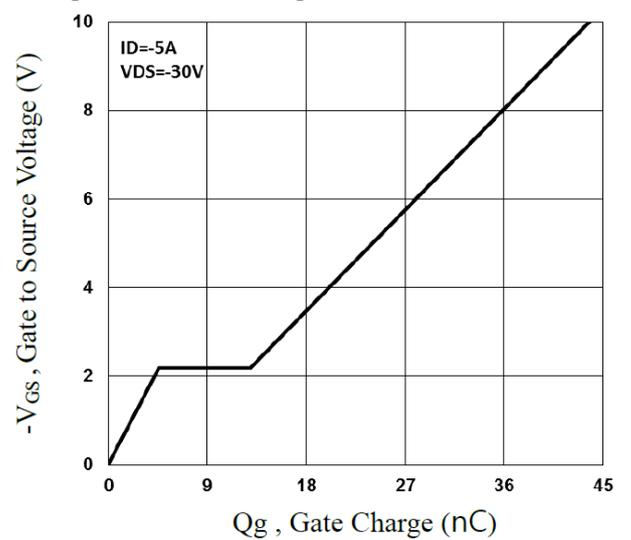


Figure 5: Normalized Transient Response

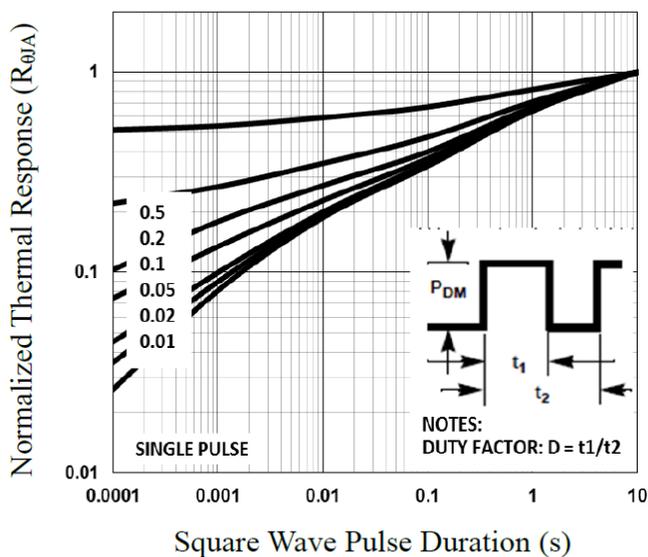


Figure 6: Maximum Safe Operation Area

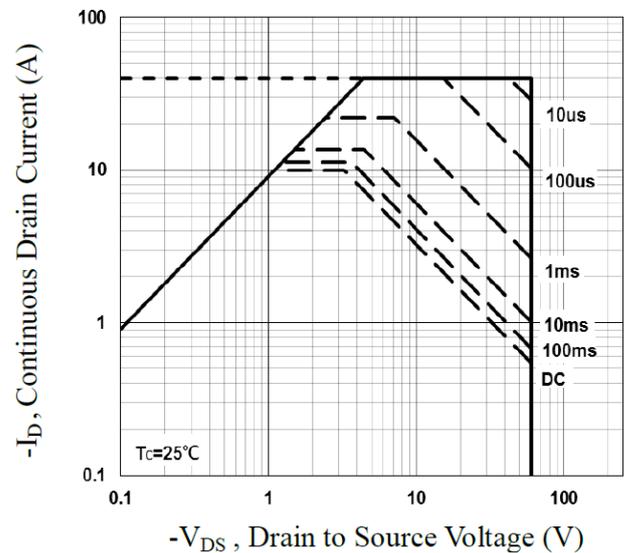


Figure 7: Switching Time Waveform

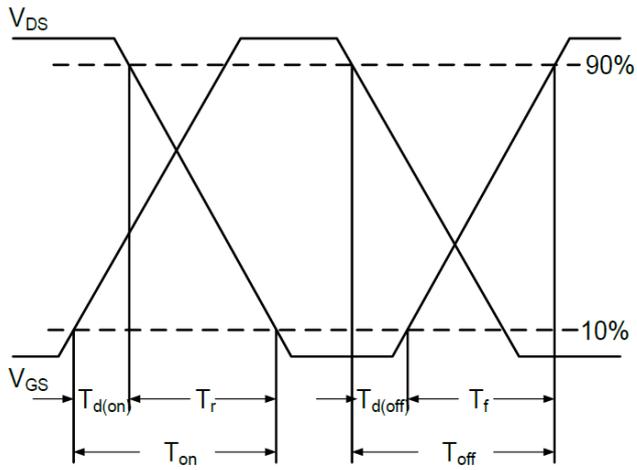
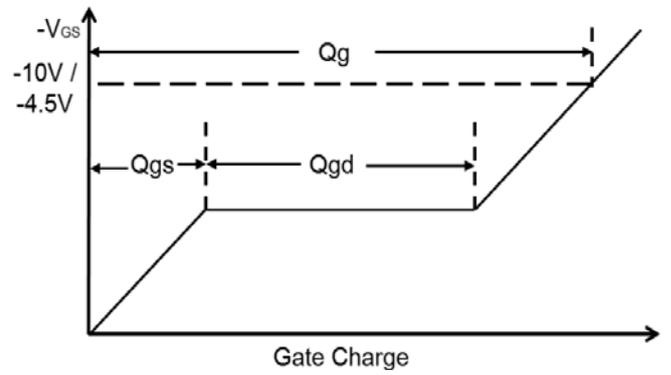
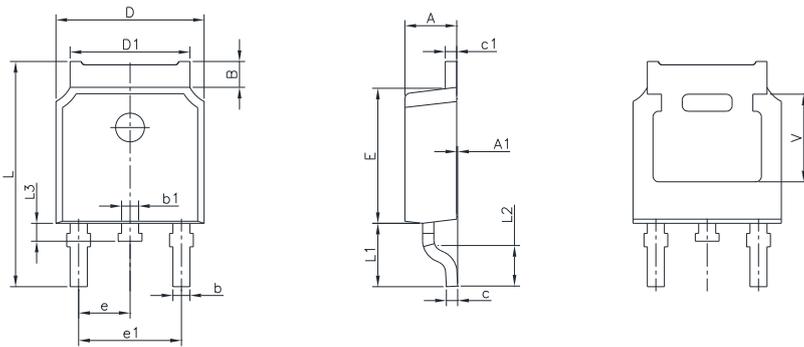


Figure 8: Gate Charge Waveform



## PACKAGE MECHANICAL DATA

### TO-252-2 Package Dimension



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.200	2.400	0.087	0.094
A1	0.000	0.127	0.000	0.005
B	1.070	1.220	0.042	0.048
b	0.720	0.850	0.028	0.033
b1	0.720	0.850	0.028	0.033
c	0.450	0.620	0.017	0.024
c1	0.450	0.620	0.017	0.024
D	6.350	6.650	0.250	0.262
D1	5.200	5.400	0.205	0.213
E	5.900	6.200	0.232	0.244
e	2.300 TYP.		0.091 TYP.	
e1	4.500	4.700	0.177	0.185
L	9.500	10.60	0.374	0.396
L1	2.550	2.900	0.100	0.114
L2	1.400	1.780	0.055	0.070
L3	0.600	0.900	0.024	0.035
V	3.950 REF.		0.155 REF.	

### Ordering information

Part number	Package	Marking	Packing	Quantity
ADM35P06E	TO-252-2	ADM35P06E	Tube	80pcs
			Embossed tape	2500pcs